IEC 63287-4

Edition 1.0 2026-08

INTERNATIONAL STANDARD

Semiconductor devices - Guidelines for reliability qualification plans - Part 4: Early failure assessment

ICS 31.080.01

ISBN 978-2-8327-1461-4

IEC 63287-4:2026-08(en)

THIS PUBLICATION IS COPYRIGHT PROTECTED
Copyright © 2026 IEC, Geneva, Switzerland

All rights reserved. Unless otherwise specified, no part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from either IEC or IEC's member National Committee in the country of the requester. If you have any questions about IEC copyright or have an enquiry about obtaining additional rights to this publication, please contact the address below or your local IEC member National Committee for further information.

IEC Secretariat
3, rue de Varembé
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
info@iec.ch
www.iec.ch

About the IEC
The International Electrotechnical Commission (IEC) is the leading global organization that prepares and publishes International Standards for all electrical, electronic and related technologies.

About IEC publications
The technical content of IEC publications is kept under constant review by the IEC. Please make sure that you have the latest edition, a corrigendum or an amendment might have been published.

IEC publications search - webstore.iec.ch/advsearchform
The advanced search enables to find IEC publications by a variety of criteria (reference number, text, technical committee, …). It also gives information on projects, replaced and withdrawn publications.

IEC Just Published - webstore.iec.ch/justpublished
Stay up to date on all new IEC publications. Just Published details all new publications released. Available online and once a month by email.

IEC Customer Service Centre - webstore.iec.ch/csc
If you wish to give us your feedback on this publication or need further assistance, please contact the Customer Service Centre: sales@iec.ch.

IEC Products & Services Portal - products.iec.ch
Discover our powerful search engine and read freely all the publications previews, graphical symbols and the glossary. With a subscription you will always have access to up to date content tailored to your needs.

Electropedia - www.electropedia.org
The world's leading online dictionary on electrotechnology, containing more than 22 500 terminological entries in English and French, with equivalent terms in 25 additional languages. Also known as the International Electrotechnical Vocabulary (IEV) online.

Warning! Make sure that you obtained this publication from an authorized distributor.

CONTENTS

FOREWORD 2
1 Scope 4
2 Normative references 4
3 Terms and definitions 4
4 Early failure assessment 4
4.1 General 4
4.2 Early failure assessment for zero failure case 5
4.2.1 General 5
4.2.2 Early failure assessment with χ^2 distribution function 6
4.2.3 Early failure assessment when employing Weibull distribution 7
Annex A (informative) Early failure deriving at the distribution function in case of zero failures 8
A.1 Summary of confidence interval in case of zero failures 8
A.2 Estimation of cumulative failure probability based on χ^2 distribution 8
A.3 Estimation of cumulative failure probability based on Weibull distribution transformation 10
A.4 Estimating cumulative failure probability when using binomial distribution 12
Annex B (informative) Equivalent failures when the number of failures is zero 13
B.1 Comparison of upper limit of one-sided early failure assessment 13
B.2 Substitute value (S,V) in case of zero failure for Method A 14
B.3 Substitute value (S,V) in case of zero failure for Methods B and C 14
Bibliography 15

Table 1 – Confidence level (C.L.) 60 % (α = 0,4) Upper limit of one-sided early failure assessment of cumulative failure probability 5
Table 2 – Confidence level (C.L.) 90 % (α = 0,1) Upper limit of one-sided early failure assessment of cumulative failure probability 6
Table B.1 – Substitute value in case of zero failure for one-sided early failure assessment (confidence level (C.L.) 60 % [α = 0,4]) 13
Table B.2 – Substitute value in case of zero failure for one-sided early failure assessment (confidence level (C.L.) 90 % [α = 0,4]) 14

INTERNATIONAL ELECTROTECHNICAL COMMISSION

_____

Semiconductor devices - Guidelines for reliability qualification plans - Part 4: Early failure assessment

FOREWORD

1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
5) IEC itself does not provide any attestation of conformity. Independent certification bodies provide conformity assessment services and, in some areas, access to IEC marks of conformity. IEC is not responsible for any services carried out by independent certification bodies.
6) All users should ensure that they have the latest edition of this publication.
7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
9) IEC draws attention to the possibility that the implementation of this document may involve the use of (a) patent(s). IEC takes no position concerning the evidence, validity or applicability of any claimed patent rights in respect thereof. As of the date of publication of this document, IEC had not received notice of (a) patent(s), which may be required to implement this document. However, implementers are cautioned that this may not represent the latest information, which may be obtained from the patent database available at https://patents.iec.ch. IEC shall not be held responsible for identifying any or all such patent rights.

IEC 63287-4 has been prepared by IEC technical committee 47: Semiconductor devices. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
47/3025/FDIS	47/3034/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

This International Standard is to be read in conjunction with IEC 63287-1.

A list of all parts in the IEC 63287 series, published under the general title *Semiconductor devices - Guidelines for reliability qualification plans*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

– reconfirmed,

– withdrawn, or

– revised.

1 Scope

This part of IEC 63287 gives guidelines for the development of reliability qualification plans using the early failure assessment, based on the environmental conditioning and proposed usage of the product. This document is not intended for military- and space-related applications.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 63287-1, *Semiconductor devices - Generic semiconductor qualification guidelines - Part 1: Guidelines for IC reliability qualification*

3 Terms and definitions

No terms and definitions are listed in this document.

ISO and IEC maintain terminology databases for use in standardization at the following addresses:

– IEC Electropedia: available at https://www.electropedia.org/
– ISO Online browsing platform: available at https://www.iso.org/obp

4 Early failure assessment

4.1 General

This is estimate of the confidence interval of the early failure assessment.